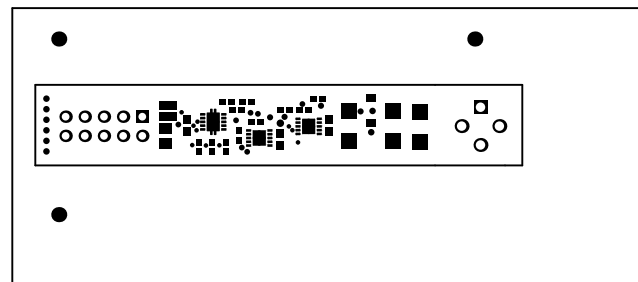
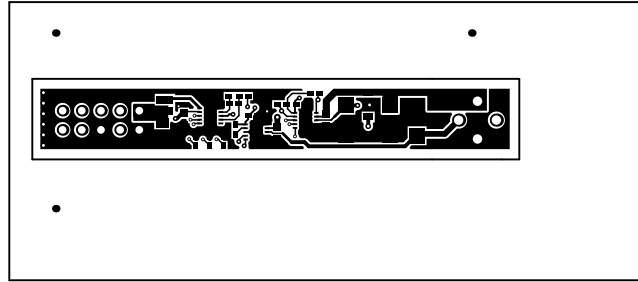


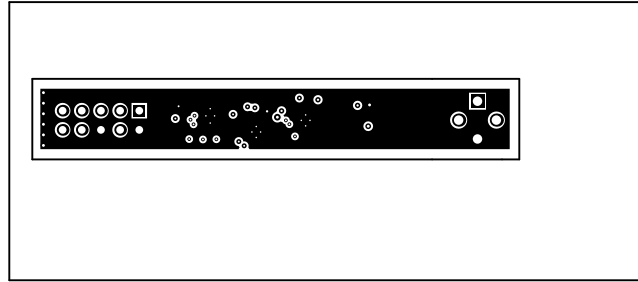
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01478	REV:	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01478		
PLOT NAME = Top Overlay	GENERATED : 8/15/2017 1:44:41 PM	TEXAS INSTRUMENTS	



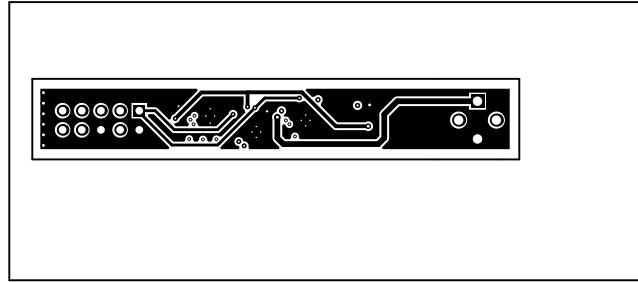
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01478	REV:	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01478		
PLOT NAME = Top Solder Mask	GENERATED : 8/15/2017 1:44:43 PM	TEXAS INSTRUMENTS	



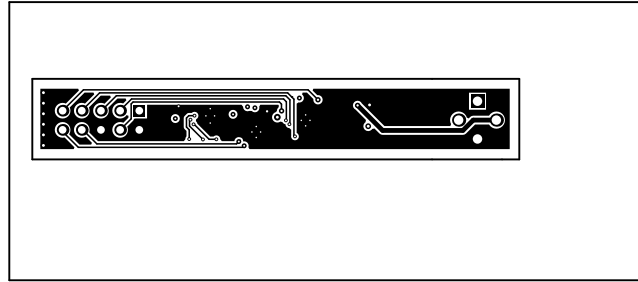
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01478	REV:	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01478		
PLOT NAME = Top Layer	GENERATED : 8/15/2017 1:44:45 PM	TEXAS INSTRUMENTS	



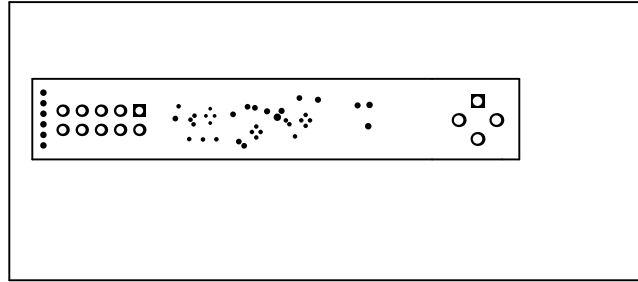
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01478	REV:	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01478		
PLOT NAME = Signal Layer 1	GENERATED : 8/15/2017 1:44:47 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01478	REV:	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01478		
PLOT NAME = Signal Layer 2	GENERATED : 8/15/2017 1:44:48 PM	TEXAS INSTRUMENTS	



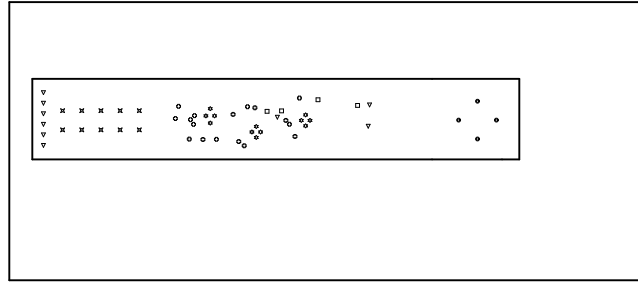
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01478	REV:	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01478		
PLOT NAME = Bottom Layer	GENERATED : 8/15/2017 1:44:50 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01478	REV:	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01478		
PLOT NAME = Bottom Solder Mask	GENERATED : 8/15/2017 1:44:52 PM	TEXAS INSTRUMENTS	

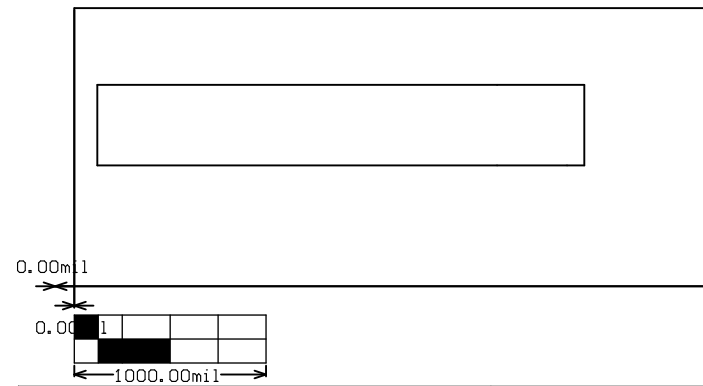


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01478	REV:	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01478		
PLOT NAME = Bottom Overlay	GENERATED : 8/15/2017 1:44:54 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01478	REV:	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01478		
PLOT NAME = Drill Drawing	GENERATED : 8/15/2017 1:44:56 PM	TEXAS INSTRUMENTS	

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
⊗	12	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
⊙	17	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
□	4	12.00mil (0.305mm)	PTH	Round	Top Layer - Bottom Layer	
▽	9	15.00mil (0.381mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	10	40.16mil (1.020mm)	PTH	Round	Top Layer - Bottom Layer	
⊙	4	49.21mil (1.250mm)	PTH	Round	Top Layer - Bottom Layer	
	56 Total					



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01478	REV:	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01478		
PLOT NAME = Board Dimensions	GENERATED : 8/15/2017 1:44:58 PM	TEXAS INSTRUMENTS	

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